



VMDSEMI

VUTP004R031NA

Datasheet



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3.1mΩ, 40V, N-Channel Power MOSFET
VUTP004R031NA
General Description
Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
40V	3.1mΩ@10V	130A
	4.0mΩ@4.5V	

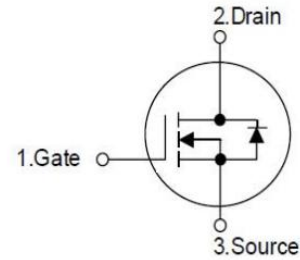


Figure 1 Symbol of VUTP004R031NA

Features

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Battery protection applications
- Power Switch Application

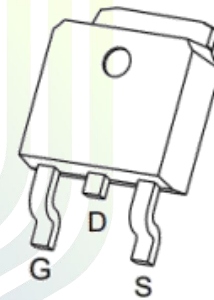
Package Type

TO-263-2L

Figure 2 Package Type of VUTP004R031NA

Ordering Information

Product Name	Package
VUTP004R031NA	TO-263-2L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	$T_C = 25\text{ °C}$	A
Continuous Drain Current ^{Note1}		$T_C = 100\text{ °C}$	
Pulsed Drain Current ^{Note2}	I_{DM}	520	
Avalanche Current ^{Note3}	I_{AS}	52	A
Single Pulsed Avalanche Energy ^{Note3}	E_{AS}	676	mJ
Total Power Dissipation ^{Note5}	P_D	$T_C = 25\text{ °C}$	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note6}	$R_{\theta JA}$		60		°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$		0.8		°C/W

Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage ^{Note4}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	3.0	V
Static Drain-Source On-Resistance ^{Note4}	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$		2.5	3.1	mΩ
		$V_{GS}=4.5V, I_D=20A$		2.9	4.0	
Forward Transconductance ^{Note4}	g_{FS}	$V_{DS}=10V, I_D=10A$	10	26		S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=20V$		13003		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		806		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		886		pF
Total Gate Charge	Q_g	$V_{DS}=20V$		230		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		29		
Gate-Drain Charge	Q_{gd}	$I_D=20A$		37		
Gate Resistance	R_g	$f=1MHz, \text{Open drain}$		1.3		Ω
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=20V$		13		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		9		
Turn-off Delay Time	$t_{d(off)}$	$R_L=0.75\Omega$		57		
Turn-off Fall Time	t_f	$R_G=3\Omega$		35		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V_{SD}	$V_{GS}=0V, I_S=20A$			1.2	V
Diode Reverse Recovery Time	t_{rr}	$I_F=20A, dI/dt=500A/ms$		20		ns
Diode Reverse Recovery Charge	Q_{rr}	$I_F=20A, dI/dt=500A/ms$		60		nC

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink.
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD}=40V, V_{GS}=10V, L=0.5mH, R_G=25\Omega$ Starting $T_J=25^\circ C$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)}=150^\circ C$.And device mounted on a large heatsink
- 6.Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$.

Typical Performance Characteristics

Figure 3: Transfer Characteristics

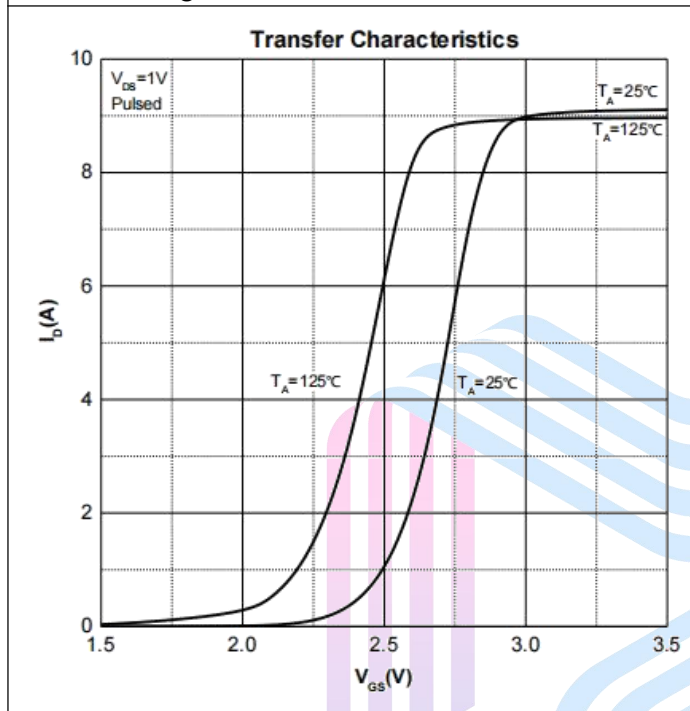


Figure 4: Output Characteristics

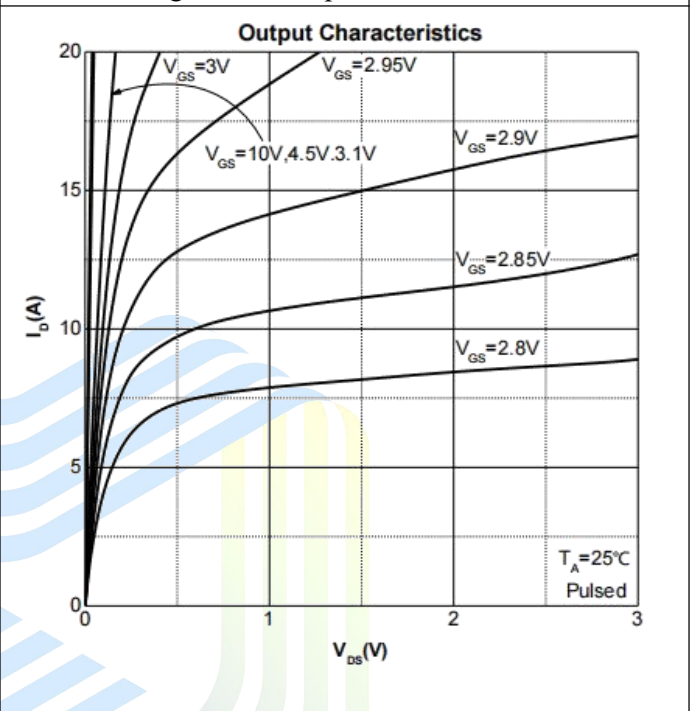


Figure 5: On-Resistance vs. Drain Current

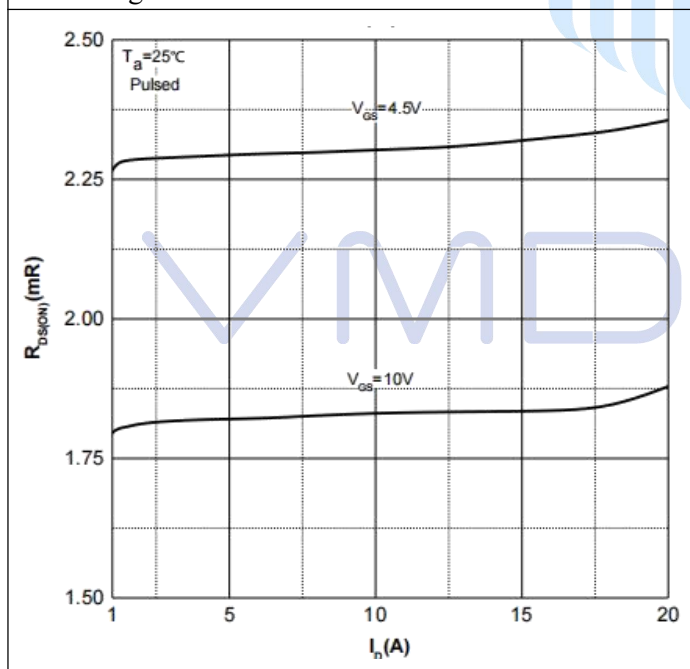


Figure 6: On-Resistance vs. Gate Voltage

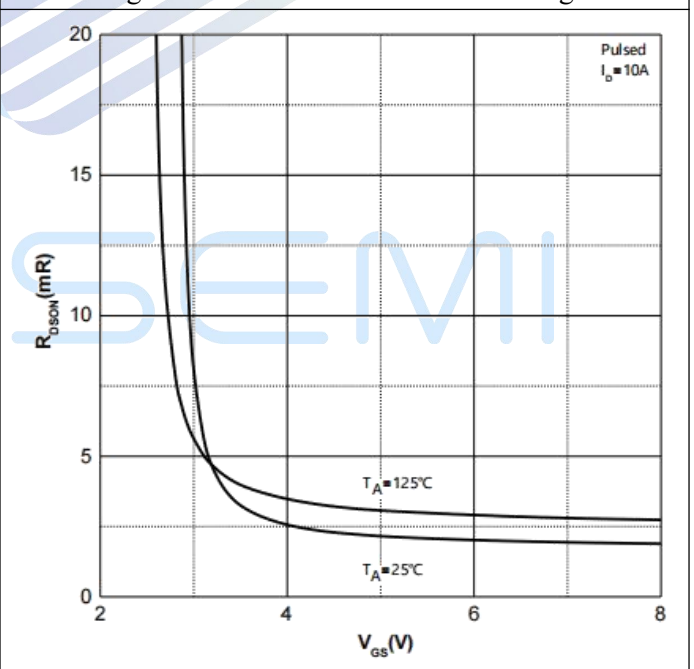


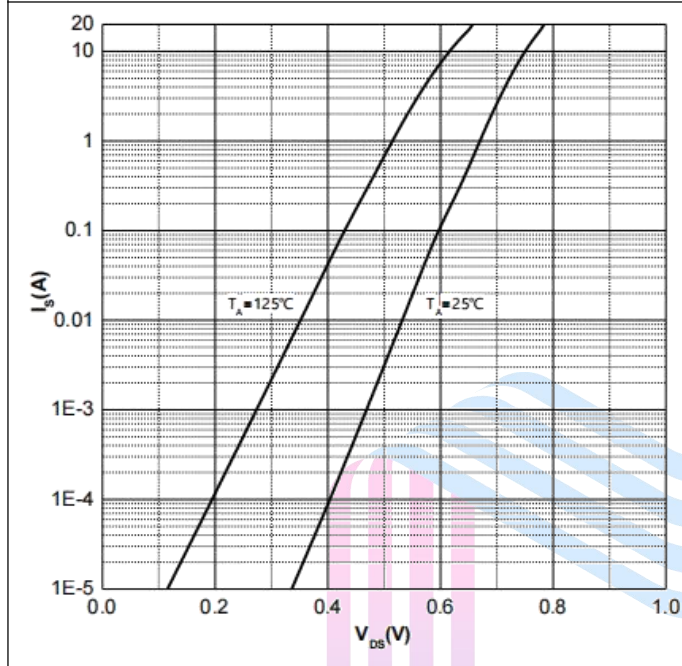
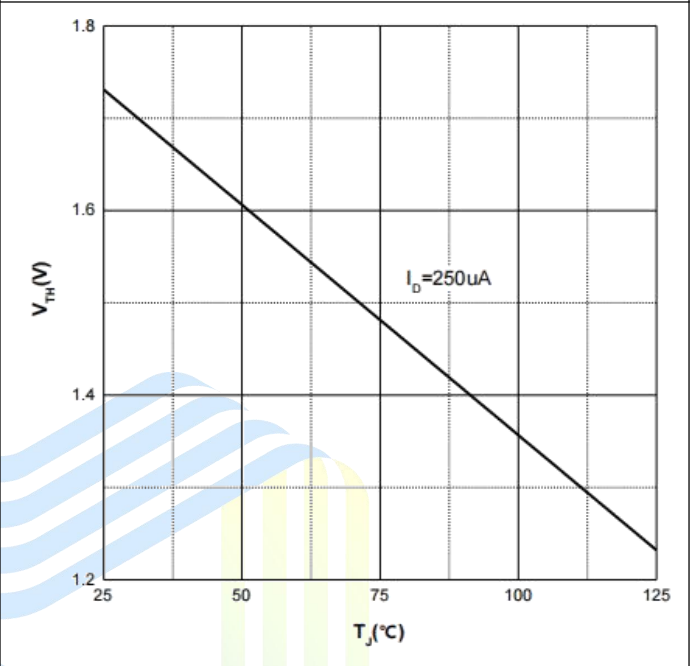
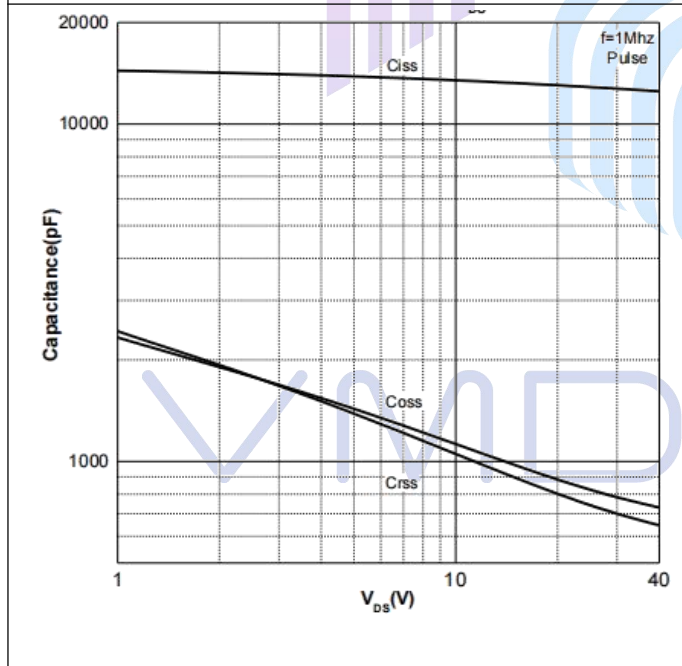
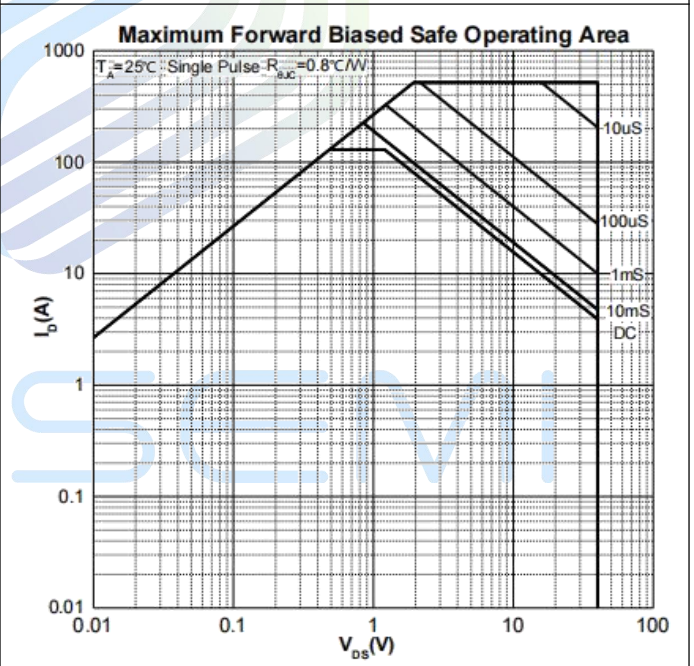
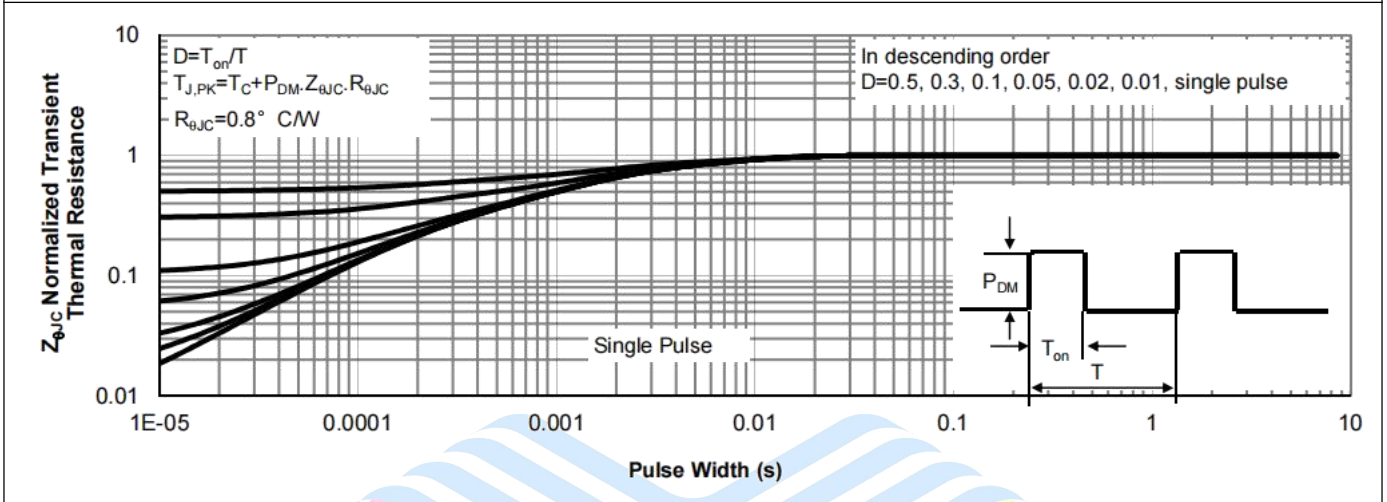
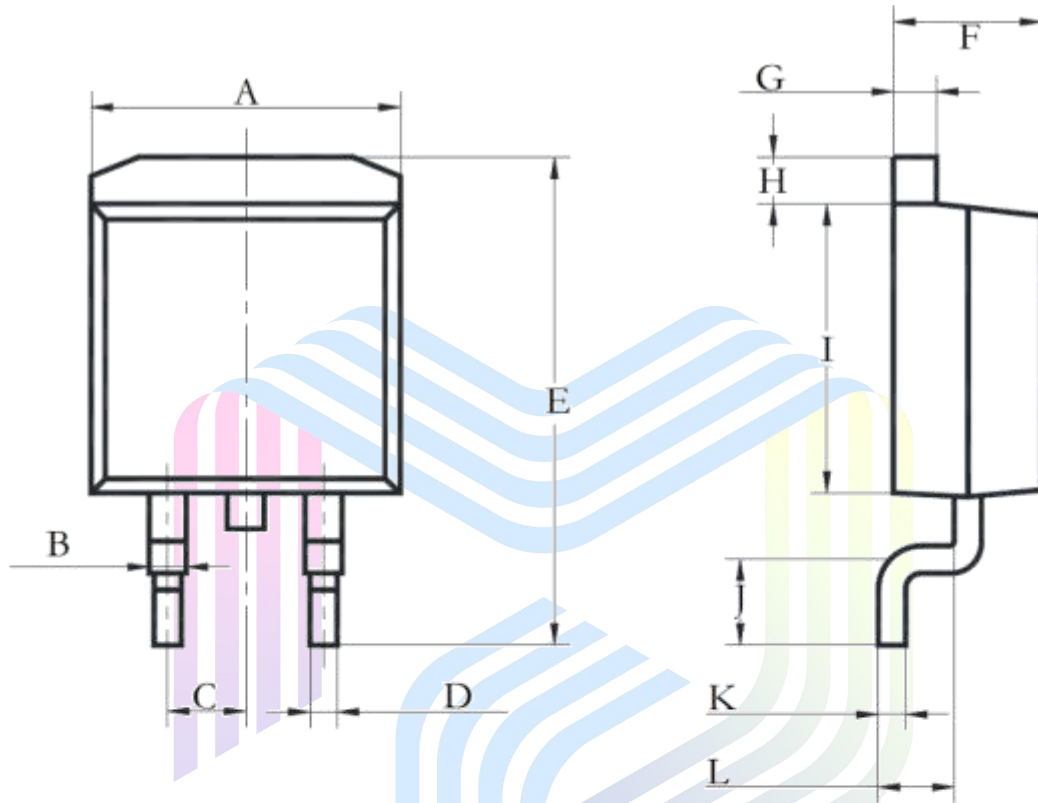
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operation Area


Figure 11: Normalized Maximum Transient Thermal Impedance




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Mechanical Dimensions:
TO-263-2L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	9.600	10.500	0.378	0.413
B	1.000	1.400	0.039	0.055
C	2.540REF		0.100REF	
D	0.680	0.940	0.027	0.037
E	14.600	15.880	0.575	0.625
F	4.400	4.800	0.173	0.189
G	1.140	1.400	0.045	0.055
H	1.140	1.400	0.045	0.055
I	8.250	9.650	0.325	0.380
J	2.290	2.790	0.090	0.110
K	0.360	0.650	0.014	0.026
L	2.030	2.790	0.080	0.110

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Via-Media Semiconductor Limited Company

<http://www.vmdsemi.com>

Main Sites:

- Headquarters

Hangzhou Via-Media Semiconductor Co., LTD.
1305-1306, Building 71, No. 90, Wensan Road, Xihu
District, Hangzhou, Zhejiang Province, P.R. China
Tel: +86-0571-8515 0563

- Chengdu Office

Chengdu Winhi Semiconductor Co., LTD.
Floor 15, Building 5, No. 171, Hele 2nd Street,
Chengdu, Sichuan Province, P.R. China
Tel: +86-028-8505 0771

- Shanghai

Shanghai R&D Center.
1506~1508, Xinyin Building, 888 Yishan Road,
Shanghai, P.R of China
Tel: +86- 021-54201999

- Shenzhen

Shenzhen Sales office
Room 4A15, Block AB, Tianxiang Building,
Chegongmiao , Futian District, Shenzhen, P.R of China
Tel: +86-0755- 82570682

- Xi'an

Xi'an R&D Center
1703B, Building A, Greenland Center, Jinye Road,
High-Tech Zone, Xi'an, Shaanxi, P.R of China